

TWO-PART THERMALLY CONDUCTIVE LIQUID GAP FILLER, 3.0 W/m-K

Features and Benefits

- Superior thermal performance
- 3.0 W/m-K thermal conductivity
- Easy to dispense
- Easy storage
- Ultra-conforming for fragile and low stress applications
- Ambient or accelerated cure schedules in elevated temperature



Cartridges



Kits

Typical Applications

- Automotive electronics
- PCBA to housing
- Discrete components to housing
- Fiber optic telecommunications equipment

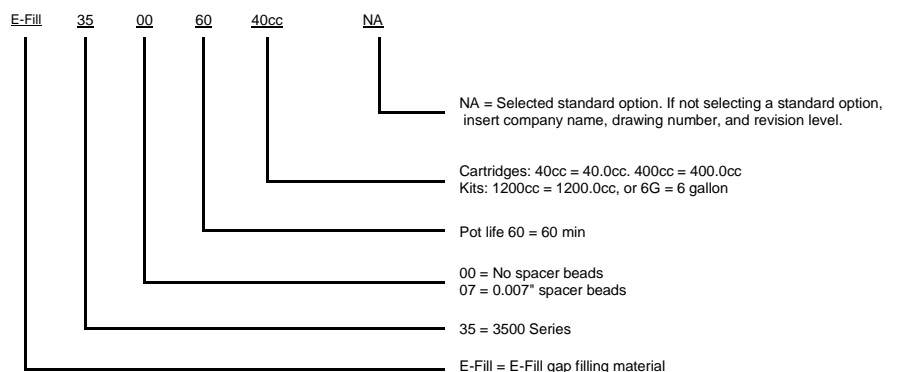
E-Fill 3500 offers excellent thermal performance and superior conformability. It is a two-component liquid gap filling material, cured at either room or elevated temperature to speed up the curing process. The pre-curing material possesses good thixotropic characteristics as well as low viscosity which is an ideal solution for dispensing. After cured, the mixture became a low modulus elastomer to relieve stresses during thermal cycling.

E-Fill 3500 will lightly adhere to surfaces, thus improving surface area contact.

| PROPERTIES | E-Fill 3500 | Test Method |
|---------------------------------|-----------------------------------|-------------|
| Construction & Composition | Soft silicone elastomer | — |
| Color | Part A: White / Part B: Blue | Visual |
| Viscosity (Spindle#6 @ 12 RPM) | Part A: 78000cP / Part B: 87000cP | ASTM D2196 |
| Density | 3.0 g/cm ³ | — |
| Mix Ratio | 1:1 | — |
| Shelf Life @ 25 °C | 5 months | — |
| PROPERTIES AS CURED | | |
| Color | Blue | Visual |
| Hardness | 55 Shore 00 | ASTM D2240 |
| Continuous Use Temp | -60 to 200 °C | — |
| Thermal Conductivity | 3.0 W/m-K | ASTM D5470 |
| Dielectric Strength | 250 V/mil | ASTM D149 |
| Dielectric Constant @ 1MHz | 12.4 | ASTM D150 |
| Volume Resistivity | 10 ¹³ ohm.cm | ASTM D257 |
| Flame Rating | V-O | U.L. 94 |
| CURE SCHEDULE | | |
| Pot Life @ 25 °C | 60 min | — |
| Cure @ 25 °C | 10 hours | — |
| Cure @ 80 °C | 10 min | — |

Please contact us for other special requirements

Product Code and Descriptions



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产品特点

- 出众的导热性能
- 导热率 3.0.W/m-K
- 适合点胶
- 易于储存
- 超好贴服性，针对易碎和低压应用设计
- 可室温固化或加速固化



筒装



桶装

一般应用

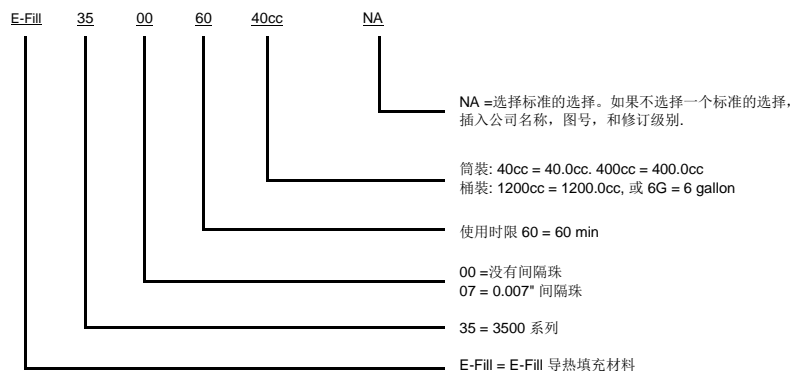
- 汽车电子
- 独立元器件到外壳
- 印制电路板装配到外壳
- 光纤通讯设备

E-Fill 3500 具有优异的热性能和卓越的舒适性。它是一种双组份液体的空隙填充材料，可经由常温自然固化或高温加速固化成型。固化前材料具有良好的触变性以及低粘度，使 E-Fill 3500 适合用于点胶上。固化后，混合成型后为一个低模量弹性体，在热循环组件中缓冲压力。

E-Fill 3500 带有轻微黏性从而提高接触面积，加强其导热效果。

| 固化前特性 | E-Fill 3500 | 测试方法 |
|-------------------|-------------------------------|------------|
| 成份 | 聚硅酮弹性体 | — |
| 外观 | A 组分: 白色 / B 组分: 蓝色 | Visual |
| 稠度 | A 组分: 78000cP / B 组分: 87000cP | ASTM D2196 |
| 密度 | 3.0 g/cm ³ | ASTM D792 |
| 混合比 | 1:1 | — |
| 保质期 @ 25 °C | 5 个月 | — |
| 固化后特性 | | |
| 颜色 | 蓝色 | Visual |
| 硬度 | 55 Shore 00 | ASTM D2240 |
| 连续使用温度 | -60 to 200 °C | — |
| 导热率 | 3.0 W/m-K | ASTM D5470 |
| 介电强度 | 250 V/mil | ASTM D149 |
| 介电常数@ 1MHz | 12.4 | ASTM D150 |
| 体积电阻率 | 10 ¹³ ohm.cm | ASTM D257 |
| UL 防火评级 | V-O | U.L. 94 |
| 固化设定 | | |
| 使用时限@ 25 °C (min) | 60 min | — |
| 固化@ 25 °C (hrs) | 10 hours | — |
| 固化@ 80 °C (min) | 10 min | — |
| 如有其他特殊要求，请联系我们 | | |

产品编码及描述



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